EMC: EV 548525916 US

□ Original Application □ V.S. Designated Office □ Continuation or Divisional Application □ Continuation-in-Part Application □ Combined Declaration, COMBINED Declaration, POWER OF ATTORNEY AND PETITION As a below named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ADHESION-ENHANCED POLYIMIDE FILM, PROCESS FOR ITS PRODUCTION, AND LAMINATED BODY □ which is described in the specification and claims □ attached hereto. □ filed on □ filed on □ filed on □
Continuation or Divisional Application Continuation-in-Part Application COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION As a below named inventor, I hereby declare that: My residence, post office address and citizenship are as stated below next to my name, I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ADHESION-ENHANCED POLYIMIDE FILM, PROCESS FOR ITS PRODUCTION, AND LAMINATED BODY which is described in the specification and claims attached hereto.
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I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ADHESION-ENHANCED POLYIMIDE FILM, PROCESS FOR ITS PRODUCTION, AND LAMINATED BODY which is described in the specification and claims attached hereto.
names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ADHESION-ENHANCED POLYIMIDE FILM, PROCESS FOR ITS PRODUCTION, AND LAMINATED BODY which is described in the specification and claims attached hereto.
attached hereto.
☐ filed on
Application Serial No.
and was amended on
(if applicable) Which is described in International Application No. PCT/JP2005/004014
filed on March 2, 2005 and as amended on
(if any),
which I have reviewed and for which I solicit a United States patent.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to patentability as defined in 37 C.F.R. §1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION (Page 2)

			Attorney	y Docket No	
for patent or inventor's certi than the United States of An	ificate, or §365(a) merica, listed belo) of any PCT Inter ow and have also i	rnational Application which identified below any foreign	§365(b) of any foreign application(s) designated at least one country other application(s) for patent or inventor's plication on which priority is claimed:	
		2	Date of Filing		
Number 2004–084836	Country		(day,month,year)	Priority Claimed	
(Pat. Appln.)	Japan		23 / March / 2004	¹⁴ ⊠ yes □ no	
				□ yes □ no	
				□ yes □ no	
				□ yes □ no	
				□ yes □ no	
(Application Serial No.)		(Filing Date)		(Status)(patented,pending,abandoned)	
(Application Serial No.)		(Filing Date)		(Status)(patented,pending,abandoned)	
T. Daniel Christenbury Paul A. Taufer Darius C. Gambino			ooint the following registered a emark Office connected there Steven A. Nash Andrew A. Noble James E. Bauersmith	attorneys to prosecute this application rewith: Reg. No. 45,507 Reg. No. 48,651 Reg. No. 50,533	
SEND CORRESPONDENCE TO: Customer No. 035811, whose contact information IP Department of Piper Rudnick LLP One Liberty Place, Suite 4900 1650 Market Street Philadelphia, PA 19103		ormation is:	DIRECT TELEPHONE CALLS TO ATTORNEY OF RECORD AT: (215) 656-3300		

COMBINED DECLARATION, POWER OF ATTORNEY AND PETITION (Page 3)

Attorney Docket No.	SPL-06-1222
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I hereby petition for grant of a United States Letters Patent on this invention.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF SOLE OR FIRST INVENTOR Masafumi Hashimoto		r's signature sa Sumi Hashimoto	DATE July 24, 2006			
RESIDENCE	•	CITIZENSHIP				
Ube-shi, Yamaguchi, Japan		Japanese				
POST OFFICE ADDRESS c/o Ube Chemical Factory, UBE INDUSTRIES, LTD., 1978-96, Oaza Kogushi, Ube-shi, Yamaguchi 755-8633, Japan						
2. FULL NAME OF JOINT INVENTOR, IF ANY Takeshi Uekido		rissignature Keshi Vekido	DATE July 24, 2006			
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post office Address c/o Ube Chemical Factory, UBE INDUSTRIES, LTD., 1978-96, Oaza Kogushi, Ube-shi, Yamaguchi 755-8633, Japan						
3. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY TOSHIYUKI NISHINO	INVENTOR	rssignature LYNKL NLSHLNO	July 24, 2006			
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5. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY		S'S SIGNATURE	DATE			
RESIDENCE		CITIZENSHIP				
POST OFFICE ADDRESS						
6. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY		t'S SIGNATURE	DATE			
RESIDENCE		CITIZENSHIP				
POST OFFICE ADDRESS						
7. FULL NAME OF ADDITIONAL JOINT INVENTOR, IF ANY INVEN		R'S SIGNATURE DATE				
RESIDENCE		CITIZENSHIP				
POST OFFICE ADDRESS						